

B2890 Board Size (mm)

A rectangular diagram representing the PCB board. A horizontal dimension line at the bottom indicates a width of 150 mm. A vertical dimension line on the right side indicates a height of 100 mm.

BOARD's DRILL SCHEDULE (Inch)

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Min/Max
O	.01	208	YES	---
⊞	.02	20	YES	---
Φ	.041	2	YES	---
⊞	.048	39	YES	---
Θ	.13779528	4	YES	---

B2890 BOARD SPECIFICATIONS

1. Board Layers: 4

2. Layer Stack Order:

Layer1 (Artwork_1): Top Signal_2, 0.5 oz, diff. 100 ohms

Layer2 (Artwork_2): Power_1, P10V, 1 oz

Layer3 (Artwork_3): Power_2, Ground, 1oz

Layer4 (Artwork_4): Bot Signal_2, 0.5 oz, diff 100 ohms

3. Apply silkscreen on both side:

Artwork_5: Top silkscreen.

Artwork_6: Bot silkscreen.

4. Apply solder mask over bare copper on both side:

Artwork_7: Top solder mask

Artwork_8: Bottom solde mask

5. Material: FR4

6. Board thickness: 0.062'' +/- 0.010.

7. TRACE IMPEDENCE: width 5 mils traces: 50 ohms

8. Emersion gold plating over bare copper

9. All layers mininum trace width/clearence/width = 5/5/5 mils,

10. Trace width can be adusted by matching the impedance requirement by manufacturing

11. All dimensions are in inches unless otherwise noted.

Contact person:

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University of Chicago

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SCH#: B2889

SPC#: B2890

ASM#: B2891

UNIVERSITY OF CHICAGO

ELECTRONICS DEVELOPMENT GROUP

TITLE

B2890 Specification

SHEET 1 OF 1

DATE 02/01/2017

DRAWN TANG

B- 2890

REV 1.0

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